

Electronics Processing Hot Melt Adhesive for Temporarily Joining Materials

Hot melt adhesive used for temporarily joining materials for electronics when cutting or polishing.

- Features
1. Quick solidification with a low viscosity
 2. Excellent adhesive strength when temporarily joining materials
 3. Easy detachment through washing after temporarily joining materials

General Properties

		Nissin Hot Melt Adhesive TG-05
Shape		Stick
Color		Blackish brown
Viscosity (mPa·s)	100 °C	150
	80 °C	480
Softening point (°C)		55
Specific gravity		1.062
Shear strength (N/cm ²)		75
Service temperature (°C)		80 ~ 100
Remarks		Good adhesion between metals

* Note that all of the above numerical values are typical values.

* Appearance photo of hot melt adhesive



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General Properties

		Nissin Hot Melt Adhesive IT-134
Shape		Stick
Color		Yellowish brown
Viscosity (mPa·s)	100 °C	40
	80 °C	Doesn't melt
Softening point (°C)		76
Shear strength (N/cm ²)		81
Service temperature (°C)		90 ~ 110
Remarks		For sapphire, silicon wafers, metal and other materials

* Note that all of the above numerical values are typical values.